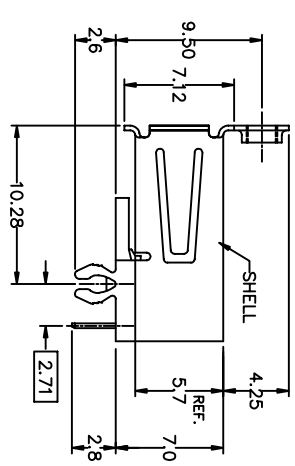
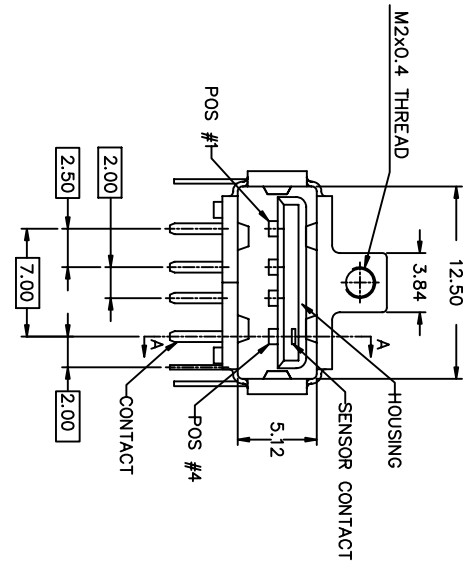
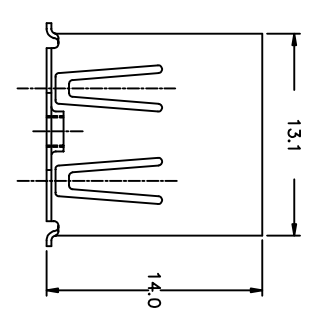
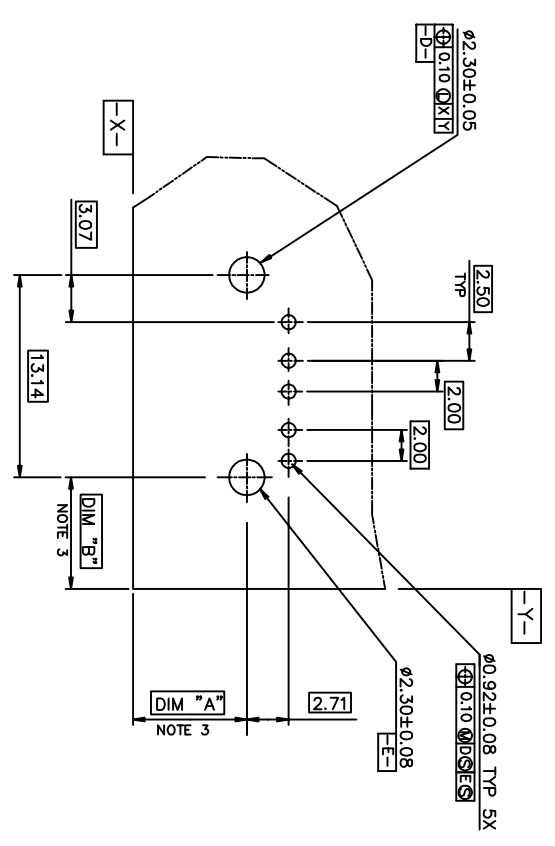


PRODUCT NO.
SEE SHEET 3



ASSEMBLY WITHOUT BACK SHIELD

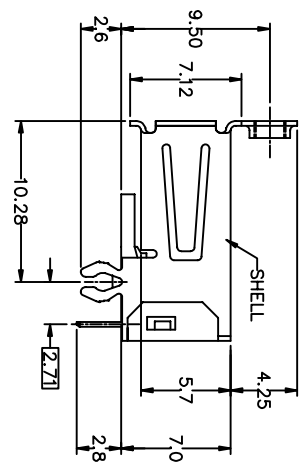
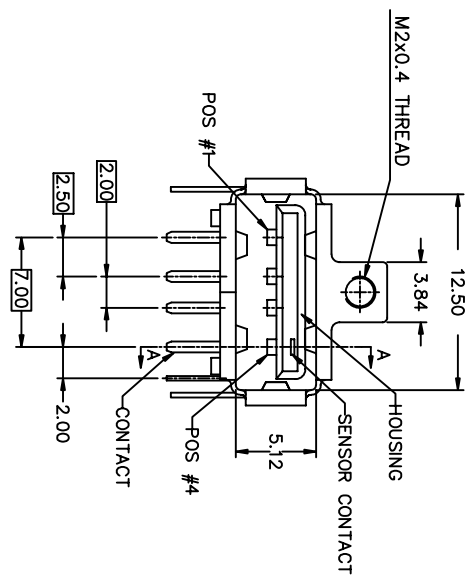
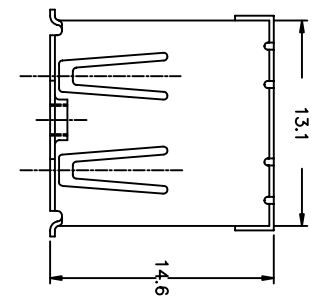


P.C. BOARD LAYOUT

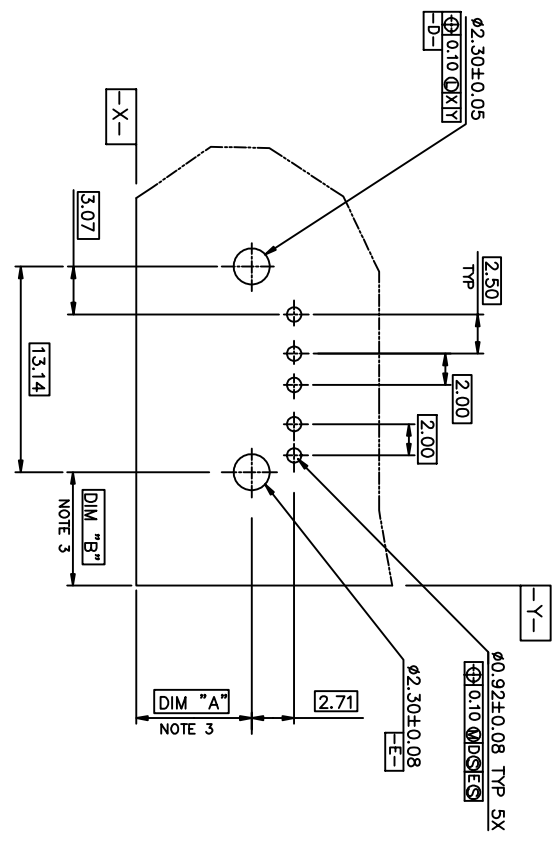
rev.	ecn no.	dr.	date	tolerance unless otherwise specified	CUSTOMER COPY	title	www.fciconnect.com
A	T70233	P P	6/18/97	.0 ± 0.30		UNIVERSAL BUS RECEPTACLE-CATALOG	
B	T70333	C L	08/11/97	.000 ± 0.10			
C	T04-0208	W L	05/13/04	± .3			
D	N04-0123	PH	12/13/04				
E	N06-0101	HB	04/13/08				
sheet revision				E	B	E	
index sheet				1	2	3	



PRODUCT NO.
 SEE SHEET 3



ASSEMBLY WITH BACK SHIELD



P.C. BOARD LAYOUT

mat'l code		tolerance unless otherwise specified		CUSTOMER COPY		title	
rev.	ecn no.	dr	date	linear	projection	unit	UNIV. SERIAL BUS S.M.T.
B				.00 ± 0.20		mm/inch	RECEPTACLE-CATALOG
				.000 ± 0.10		mm/inch	Product family USB
				± .3°		mm/inch	code
					dir	SHIPLEY HSD/01/10/97	
					engr	R Y LIU 01/10/97	
					chr	R Y LIU 01/10/97	
					pppl	JENN TSAO 01/10/97	
sheet	revision				scale	2.5:1	sheet
index	sheet					A3	2 OF

PRODUCT NUMBER CODE

61819 - X X X X X S LF

BASE PRODUCT NUMBER

HOUSING COLOR OPTIONS

- 0 - WHITE
- 1 - BLACK

PIN NO. OPTION

- 0 - 5 PIN
- 1 - 4 PIN

SHELL OPTIONS

- 1 - WITHOUT BACK SHIELD
- 2 - WITH BACK SHIELD

TERMINAL PLATING OPTION

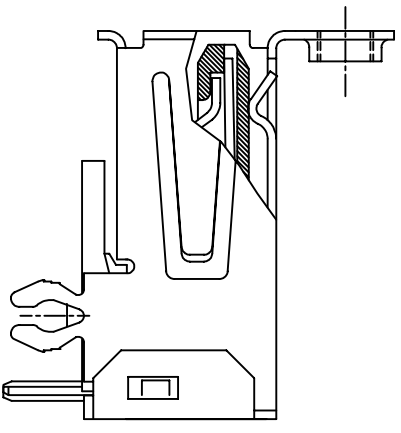
- 0 - 50u" Ni UNDERPLATE
- 30u" GXT CONTACT AREA
- 100u" TIN/LEAD TAIL AREA
- 1 - 50u" Ni UNDERPLATE
- 30u" GXT CONTACT AREA
- 100u" TIN TAIL AREA

PACKAGING OPTION

- B - TUBES

ONLY FOR PANASONIC

LEAD FREE OPTION
 WHEN "TERMINAL PLATING OPTION" IS 1



SECTION A-A

NOTES:

1. MATERIAL: PHOSPHOR BRONZE
 CONTACTS: PHOSPHOR BRONZE
 SHIELD: PHOSPHOR BRONZE
 HOUSING: UL 94V-0 THERMOPLASTIC, COLOR: WHITE
2. PLATING: CONTACTS: GOLD FLASH OVER
 PALLADIUM NICKEL (0.76um MINIMUM) IN CONTACT
 AREA; 2.54 um TIN-LEAD OR TIN MINIMUM IN SOLDER TAIL AREA.
 1.27 um MINIMUM NICKEL UNDERPLATE OVER ALL SURFACES.
 SHIELD: 2.54 um MINIMUM TIN/LEAD OR TIN OVER 1.27 um
 MINIMUM NICKEL UNDERPLATE
3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER.
4. RECOMMENDED BOARD THICKNESS IS 0.8~1.2 mm.
5. MAXIMUM PANEL THICKNESS TO BE 2.67 mm IF MOUNTED
 BEHIND PANEL.
6. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD
 FREE P/N'S
7. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION
 DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN
 GS-22-008
8. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE
 TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION,
 INFRO-RED OR VAPOR PHASE REFLOW OVEN.

mat'l code	tolerance unless otherwise specified	CUSTOMER COPY	title	code
rev. econ no. dr.	date			
E	linear .00 ± 0.20 angular .000 ± 0.10 angles ± 3°	projection	UNIV. SERIAL BUS RECEPTACLE	sheet 3 OF
		Shirley HSU 07/10/97	product family	
		enr R Y LUU 07/10/97	size	
		chr R Y LUU 07/10/97	dwg no.	61819
		qppd JENN TSAO 07/10/97	scale	A3
sheet revision				
index sheet				